TWEPP 2017 Topical Workshop on Electronics for Particle Physics



Contribution ID: 196 Type: Oral

System Integration: Integrated IC/Package/PCB Together

- a. Implementation flow
- b. Analysis flow

Summary

 $\textbf{Presenter:} \quad \textbf{CHEN (SR. STAFF APPLICATION ENGINEER CUSTOM IC \& SIMULATION - CADENCE DESIGN } \\$

SYSTEMS), Ping

Session Classification: TUTORIAL